



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10A105KO8NNND

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 1 µF, 16V, ±10%, X5R, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>A</u> <u>105</u> <u>K</u> <u>O</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>D</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor								
2	Size	0603 (ii	nch code)	L:	1.6	± 0.1	mm	W:	0.8 ± 0.1	mm
3	Dielectric	X5R			8	Inner e	electrode	N	li	
4	Capacitance	1 µ	=		_	Termi	nation	C	Cu	
(5)	Capacitance	±10 %)			Plating	g	S	in 100%	(Pb Free)
	tolerance				9	Produ	ct	N	Iormal	
6	Rated Voltage	16 V			10	Specia	al	R	Reserved for	future use
7	Thickness	0.8 ±	0.1 mm		11)	Packa	ging	C	ardboard T	ype, 13" reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms					
Tan δ (DF)	0.05 max.						
Insulation	10,000Mohm or 100Mohm⋅ <i>µ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X5R						
characteristics	(From -55℃ to 85℃, Capacitance change should be within ±15%)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120 ℃ for 10~30sec.)					
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)
		2hours × 3 direction (x, y, z)
Moisture	Capacitance change: within ±12.5%	With rated voltage
Resistance	Tan δ : 0.075 max	40±2°C, 90~95%RH, 500+12/-0hrs
	IR: 500Mohm or 25Mohm · μF	
	Whichever is Smaller	
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage
Resistance	Tan δ : 0.075 max	Max. operating temperature
	IR: 1000Mohm or 50Mohm $\cdot \mu$ F	
	Whichever is Smaller	1000+48/-0hrs
Temperature	Capacitance change : within ±7.5%	1 cycle condition
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C
		→ Max. operating temperature → 25°C
		5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C , 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.